

Model : EBA35001-6

BGA Heat Sink Specification

For 35x35 Chip set

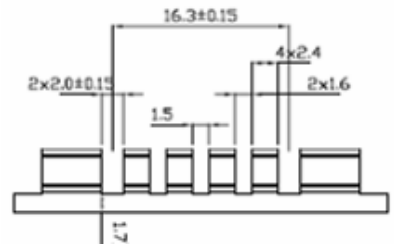
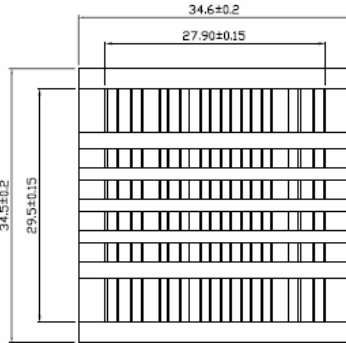


1. Material : Al 6063

2. Dimension :
 Foot print : 35x35mm
 Height : 6 mm
 Base (thickness) : 1.7mm

3. Finish: Black Anodize

4. Accessory :
 Clip : Plastic (UL94-V0)
 Thermal pad : 8612I or others



Performance

Heat Source (LxW)	15x15
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